

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/04/2022

Details for "OPA354AQDBVRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
OPA354AQDBVRQ1	NIPDAU	Level-2-260C-1 YEAR	Ext-Mfg	DBV 5	2.9x1.6x1.45	20.2

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.040498	100	1000000	0.200722	2007
Sub-Total			0.040498	100	1000000	0.200722	2007
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.09389	74.9998	749998	0.465351	4654
Thermoplastics	Epoxy	85954-11-6	0.031297	25.0002	250002	0.155119	1551
Sub-Total			0.125187	100	1000000	0.620469	6205
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	7.80776	97.597	975970	38.697916	386979
Copper and Its Alloys	Iron	7439-89-6	0.1784	2.23	22300	0.884211	8842
Copper and Its Alloys	Phosphorus	7723-14-0	0.0028	0.035	350	0.013878	139
Zinc and Its Alloys	Zinc	7440-66-6	0.01104	0.138	1380	0.054718	547
Sub-Total			8	100	1000000	39.650723	396507
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.085608	95.12	951200	0.424302	4243
Precious Metals	Gold	7440-57-5	0.000702	0.78	7800	0.003479	35
Precious Metals	Palladium	7440-05-3	0.00369	4.1	41000	0.018289	183
Sub-Total			0.09	100	1000000	0.446071	4461
Mold Compound							
Other inorganic Materials	Fused Silica	60676-86-0	9.960826	87.000002	870000	49.369244	493692
Other Plastics and Rubber	Carbon Black	1333-86-4	0.011449	0.099998	1000	0.056745	567
Thermoplastics	Epoxy	85954-11-6	1.47695	12.9	129000	7.320267	73203
Sub-Total			11.449225	100	1000000	56.746256	567463
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.471267	100	1000000	2.33576	23358
Sub-Total			0.471267	100	1000000	2.33576	23358
Total			20.176177			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSiS or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer
 TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.